Wafer Acceptance Flow for Space Qualified MMIC

1. Per P10N02, Receiving Inspection
2. Wafer Traceability, per 101099 Wafer Incoming Inspection Procedure
3. Per 101099, Wafer Incoming Inspection Procedure
4. Per W10N03, Wafer Incoming Inspection Procedure
   - Serialization
   - Backside Metal
   - Adhesion to Tape
   - Surface Defects, 50X Magnification
5. Sample Qty MMIC Visual Inspection, Per MIL-STD-883, Method 2010A
   - 100 - 500X magnification
   - 4 Die/Wafer
   - Pull 12 Wires (0 Rejects)
8. Wafer Lot Acceptance, Per MIL-STD-883, Method 5007
   - Wafer Thickness
   - Metal Thickness
   - Glassivation Thickness
   - SEM-Method 2018
9. 100% RF Probe Test
   - Per Customer PO and Customer Specification
   - Read and Record data
10. Packaging, per 118186
    - Black Conductive Waffle Pak, Black Conductive Cover & Tyvek Paper Insert (2)
    - GEL-PAK Containers Available at Customer Request
11. 100% MMIC Visual Inspection, Per MIL-STD-883, Method 2010A
    - Per Customer PO and Customer Specification
12. Lot Acceptance Testing (LAT)
    - Optional Per Customer Specification & PO
    - See Recommended QCI LAT Flow Herein
13. QA Data Review
    - Customer Source Inspection (CSI) Optional
14. Per P15N01, Handling, Storage, Packaging, Preservation & Delivery